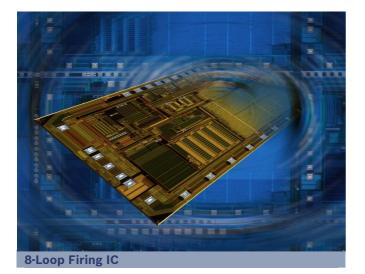
Automotive Electronics

Product Information 8-Loop Firing IC – CG988





Customer benefits:

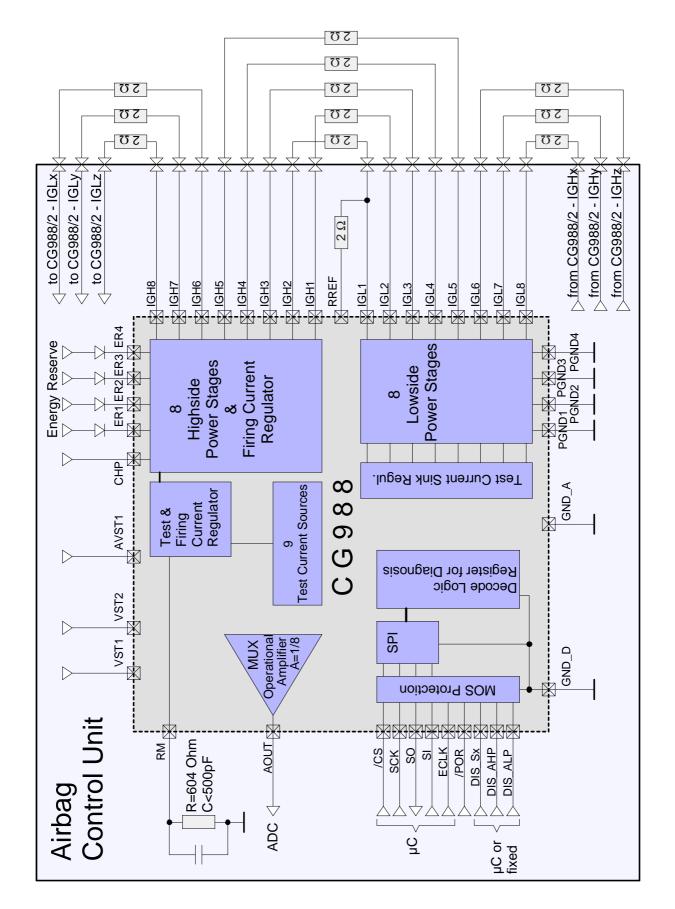
- Excellent system know-how
- Smart concepts for system safety
- Secured supply
- Long- term availability of manufacturing processes and products
- QS9000 and ISO/TS16949 certified

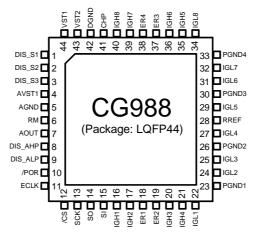
Following the successful implementation of the CG685/CG687 Quad- and Dual Firing Loop ICs, Bosch Automotive Electronics will move along with the introduction of a highly integrated version of a firing IC with 8 fully integrated squib driver channels for DC firing. The CG988 is being designed by utilizing leading-edge automotive ASIC processes with 0.8•m feature size. The superior performance with respect to precision and reliability and the well-proven safety concept of its predecessors will be combined with a variety of new features as required by the quickly evolving next generations of electronic safety systems.

Features

- Optimized firing concept with 2 firing modes for efficient energy management
- Firing current >2A for 3ms, single pulse
- Energy reserve voltage up to 35V
- Full cross coupling capability (highside and lowside drivers placed on different ASICs)
- Firing current counter, 4 bit per firing loop
- High precision firing loop diagnostics (shorts, leakage, squib resistance)
- 26 channel analog multiplexer with tristate mode to monitor squib pins and supply voltages
- Sophisticated safety concept (power-on reset, disable pins for highside and for lowside stages, redundant firing path circuitry)
- 3 safety disable pins to lock 3 groups of up to 8 firing-loops
- All functions controlled via 8MHz, 16 bit bidirectional SPI
- 5V/3.3V systems compatibility
- QFP44 package

(Example for cross coupling of firing loops 6-8 shown)





PIN description

1DIS_S1InSpecial disable of firing loops 1-8, Group 1 μ C or fixed2DIS_S2InSpecial disable of firing loops 1-8, Group 2 μ C or fixed3DIS_S3InSpecial disable of firing loops 1-8, Group 3 μ C or fixed4AVST1SupplyAnalog stabilised voltage input5V5AGNDSupplyAnalog groundGND6RMInTest current adjust $604\Omega \pm 1\%$, O7AOUTOutAnalog multiplexer output μ C, A/D8DIS_AHPInDisable all highside power stages μ C9DIS_ALPInDisable all lowside power stages μ C10/PORInExternal clock, 2 MHz μ C, Clock 2M12/CSInChip select μ C, SPI13SCKInSerial clock, 8MHz μ C, SPI, Cloce	t 1Hz
3DIS_S3InSpecial disable of firing loops 1-8, Group 3 μ C or fixed4AVST1SupplyAnalog stabilised voltage input5V5AGNDSupplyAnalog groundGND6RMInTest current adjust $604\Omega \pm 1\%, C$ 7AOUTOutAnalog multiplexer output μ C, A/D8DIS_AHPInDisable all highside power stages μ C9DIS_ALPInDisable all lowside power stages μ C10/PORInPower on reset, active lowRESET circuit11ECLKInExternal clock, 2 MHz μ C, SPI13SCKInSerial clock, 8MHz μ C, SPI, Clock	t 1Hz
4AVST1SupplyAnalog stabilised voltage input5V5AGNDSupplyAnalog groundGND6RMInTest current adjust $604\Omega \pm 1\%$, C7AOUTOutAnalog multiplexer output μ C, A/D8DIS_AHPInDisable all highside power stages μ C9DIS_ALPInDisable all lowside power stages μ C10/PORInPower on reset, active lowRESET circuit11ECLKInExternal clock, 2 MHz μ C, Clock 2M12/CSInChip select μ C, SPI13SCKInSerial clock, 8MHz μ C, SPI, Cloce	t 1Hz
5AGNDSupplyAnalog groundGND6RMInTest current adjust $604\Omega \pm 1\%$, C7AOUTOutAnalog multiplexer output μ C, A/D8DIS_AHPInDisable all highside power stages μ C9DIS_ALPInDisable all lowside power stages μ C10/PORInPower on reset, active lowRESET circuit11ECLKInExternal clock, 2 MHz μ C, Clock 2M12/CSInChip select μ C, SPI13SCKInSerial clock, 8MHz μ C, SPI, Clock	t 1Hz
5AGNDSupplyAnalog groundGND6RMInTest current adjust604Ω ± 1%, C7AOUTOutAnalog multiplexer outputµC, A/D8DIS_AHPInDisable all highside power stagesµC9DIS_ALPInDisable all lowside power stagesµC10/PORInPower on reset, active lowRESET circuit11ECLKInExternal clock, 2 MHzµC, Clock 2M12/CSInChip selectµC, SPI13SCKInSerial clock, 8MHzµC, SPI, Clock	t 1Hz
6RMInTest current adjust $604\Omega \pm 1\%$, C7AOUTOutAnalog multiplexer output μ C, A/D8DIS_AHPInDisable all highside power stages μ C9DIS_ALPInDisable all lowside power stages μ C10/PORInPower on reset, active lowRESET circuit11ECLKInExternal clock, 2 MHz μ C, Clock 2M12/CSInChip select μ C, SPI13SCKInSerial clock, 8MHz μ C, SPI, Clock	t 1Hz
8 DIS_AHP In Disable all highside power stages μC 9 DIS_ALP In Disable all lowside power stages μC 10 /POR In Power on reset, active low RESET circuit 11 ECLK In External clock, 2 MHz μC, Clock 2M 12 /CS In Chip select μC, SPI 13 SCK In Serial clock, 8MHz μC, SPI, Clock	IHz
9DIS_ALPInDisable all lowside power stagesμC10/PORInPower on reset, active lowRESET circuit11ECLKInExternal clock, 2 MHzμC, Clock 2M12/CSInChip selectμC, SPI13SCKInSerial clock, 8MHzμC, SPI, Clock	IHz
10/PORInPower on reset, active lowRESET circuit11ECLKInExternal clock, 2 MHzμC, Clock 2M12/CSInChip selectμC, SPI13SCKInSerial clock, 8MHzμC, SPI, Clock	IHz
11 ECLK In External clock, 2 MHz μC, Clock 2M 12 /CS In Chip select μC, SPI 13 SCK In Serial clock, 8MHz μC, SPI, Clock	IHz
12 /CS In Chip select μC, SPI 13 SCK In Serial clock, 8MHz μC, SPI, Clock	
13 SCK In Serial clock, 8MHz μC, SPI, Cloc	k 8MHz max.
	k 8MHz max.
14 SO Out Slave out μC, SPI	
15 SI In Slave in μC, SPI	
16 IGH1 Out Igniter loop high, channel 1 Squib loop 1	, highside
17 IGH2 Out Igniter loop high, channel 2 Squib loop 2	, highside
18 ER1 Supply Energy reserve voltage firing loop 1,2 33V±2V, ener	gy reserve
19 ER2 Supply Energy reserve voltage firing loop 3,4 33V±2V, ener	gy reserve
20 IGH3 Out Igniter loop high, channel 3 Squib loop 3	, highside
21 IGH4 Out Igniter loop high, channel 4 Squib loop 4	, highside
22 IGL1 In Igniter loop low, channel 1 Squib loop 1	, lowside
23 PGND1 Supply Power ground firing loop 1,2 GND	
24 IGL2 In Igniter loop low, channel 2 Squib loop 2	, lowside
25 IGL3 In Igniter loop low, channel 3 Squib loop 3	, lowside
26 PGND2 Supply Power ground firing loop 3,4 GND	
27 IGL4 In Igniter loop low, channel 4 Squib loop 4	, lowside
28 RREF Out Reference resistor Expected tot.	al firing loop resistance
29 IGL5 In Igniter loop low, channel 5 Squib loop 5	, lowside
30 PGND3 Supply Power Ground Firing Loop 5,6 GND	
31 IGL6 In Igniter loop low, channel 6 Squib loop 6	, lowside
32 IGL7 In Igniter loop low, channel 7 Squib loop 7	, lowside
33 PGND4 Supply Power ground riring loop 7,8 GND	
34 IGL8 In Igniter loop low, channel 8 Squib loop 8	, lowside
35 IGH5 Out Igniter loop high, channel 5 Squib loop 5	, highside
36 IGH6 Out Igniter loop high, Channel 6 Squib loop 6	, highside
37 ER3 Supply Energy reserve voltage firing Loop 5,6 33V±2V, ener	gy reserve
38 ER4 Supply Energy reserve voltage firing Loop 7,8 33V±2V, energy	gy reserve
39 IGH7 Out Igniter loop high, channel 7 Squib Loop 7	', highside
40 IGH8 Out Igniter loop high, channel 8 Squib Loop 8	3, highside
41 CHP Supply Charge pump voltage VERx+7V	
42 DGND Supply Digital ground GND	
	ording to µC)
44 VST1 Supply Digital 5V stabilized voltage input 5V	

Dual Firing Mode Concept

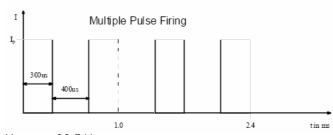
The CG988 operates in two different firing modes depending on the energy reserve voltage at pins ER1-ER4 (the proper firing mode is set by the CG988 and is not accessible by SPI command). Starting the firing sequence with an energy reserve voltage of 35V, CG988 fires with multiple pulses at high current level for an efficient energy management. The nominal firing current is 3A. As the energy reserve voltage falls beyond VER(nom)=23.5V the second mode (single pulse firing mode) is enabled with a minimal firing current of 2A. The reduced firing current for single pulse ensures full energy for the squib down to low energy reserve voltages. The pulse mode of the selected loop is determined by the ASIC and remains unchanged during the complete firing sequence. The gain in efficiency in comparison to conventional DC firing concepts is in the range of 20 to 25 percent. The dual firing mode concept operates without any additional effort by μ C.

To ensure an optimized firing of both high energy and low energy squibs two different time frames are defined: 1ms for low energy squibs and 2.5ms for their high energy counterparts. The firing sequence can be extended up to 3ms with full short circuit protection.

*RSquib=2 Ω

Maximum ratings

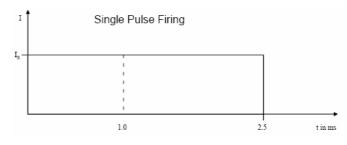
Multiple pulse firing



VER(nom) • 23.5 V

IP: 2.55A ... 3.45A, nominal 3.0A Firing time adjustable by software.

Single pulse firing



V_{ER(nom)} <23.5 V Is: 2.0A ... 2.8A, nominal 2.4A Firing time adjustable by software.

Parameter	Symbol	Min.	Тур.	Max.	Unit
Supply voltages	VER1-2	-0.3		36	V
	VCHP	-0.3		36	V
	Vvst1	-0.3		7	V
	VAVST1	-0.3		7	V
	Vvst2	-0.3		7	V
Power ground	Vpgnd12	-0.3		0.3	V
Digital ground	Vdgnd	-0.3		0.3	V
Firing loops, static	VIGH14	-0.3		36	V
	VIGL14	-0.3		36	V
	VRREF	-0.3		36	V
Junction temperature	Tj	-40		150	°C
Operating temperature	Tamb	-40		105	°C
ESD classification					
Human body model					
- All pins except VST1, VST2	Vнвм	-2000		2000	V
- VST1, VST2		-800		800	V

Electrical characteristics

Parameter	Symbol	Min.	Тур.	Max.	Unit
Supply voltages	Ver1	10		35	V
	Ver2-4	5.2		35	V
	Vснр	VERmin+7		35	V
	Vvst1	4.7	4.9	5.1	V
	VAVST1	4.7	4.9	5.1	V
	Vvst2	3.1/4.7*	3.3/4.9*	3.5/5.1*	V

Parameter	Symbol	Min.	Тур.	Max.	Unit
Current reference	Rrm		604		Ω
(AVST1=4.9V)	Irm	-4%	2	4%	mA
Test current source	· · · · · · · · · · · · · · · · · · ·				·
Ratio test/ reference current, IRM=2mA	Irref/Irm	18.5	19.75	21	
Tracking of test current source,0≤VIGH≤0.5V	Ііднх/Іідну	0.99	1.00	1.1	
Test current sink					
Saturation voltage, IIGL=40mA	Vigl	10	20	40	mV
Tracking of saturation voltage, lowside	Viglx/Vigly	-20%	1	20%	
Current limitation, VIGL<18V, t<3ms	ligl	60	120	180	mA
Voltage divider at IGLx, IGHx					
Pull up resistor for leakage tests	RIGHx, RIGLx	6	12	20	kΩ
Pull down resistor for leakage tests	Righx,Riglx	3	6	10	kΩ
Quiescent potential	Vighx,Viglx	-5%	AVST1/3	5%	V
Highside power stage					
Firing current (ton \leq 3ms, VER \leq 35V	/)				
Switching voltage between firing modes	Vsw	22	23.5	25	V
Pulse mode, VER>VSW	-lighx	2.55	3.0	3.45	A
Single pulse mode, VER <vsw< td=""><td>-lighx</td><td>2.0</td><td>2.4</td><td>2.8</td><td>A</td></vsw<>	-lighx	2.0	2.4	2.8	A
Duty cycle, pulse mode, error<1%		41.5	43	50	%
Drain-source on-state resistance (TJ≤105°C, IDs=0.5A)	RDS(on)		0.8	1.2	Ω
Drain-source voltage (TJ≤105°C, IDs=2A)	VDS(min)			3	V
Lowside power stage					
Firing current ($t_{ON} \le 2.5ms$, $V_{ER} \le 35V$)			_		
Current load capacity (TJ≤105°C)	liglx	3.5			A
Drain-source on-state resistance	RDS(on)		0.6	1.0	Ω
(TJ≤105°C, IDS=0.5A)					
Drain-source voltage (TJ≤105°C, IDS=2A)	VDS(min)			3	V
Firing current detection level					
Ver-Vigh>5V					
Multiple pulse mode	FDET(MP)	1.5		REG(MP)	A
Single pulse mode	FDET(SP)	1.2		REG(SP)	A

* VVST2 in 5V System environment

** measured with reduced accuracy; guarantied by design

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